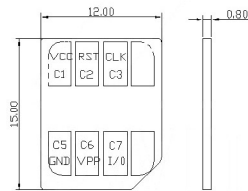
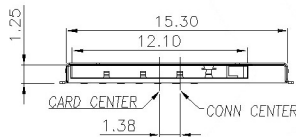
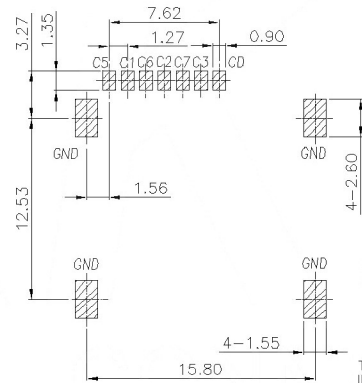


- NOTES:
- 1) MATERIAL:
HOUSING: LCP, PLASIC UL 94V-0
CONTACT: COPPER ALLOY
SHELL: STAINLESS STEEL
 - 2) FINISH:
CONTACT: GOLD FLASH PLATED ON CONTACT AREA;
GOLD FLASH PLATED ON SOLDER TAILS,
 - 3) PART NO.:

XKSMO-003-X
L1: GOLD PLATED G/F



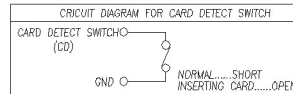
3FF SIM CARD



CIRCUT TRACE KEEP OUT AREA
 SMT SOLDER AREA
 THERE SHOULD NOT BE ANY CIRCUITRIES IN THE LAYOUT SPACE OF THE PRODUCTS.
 RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ±0.05

ITEM	PAPT NAMF	QTY	MATERIAL	FINISHING
③	Shell	1	SUS	
②	Terminal	7	COPPER ALLOY	
①	Housing	1	HI-TEMP. PLASIC UL 94V-0	BLACK

SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



MARK	DESCRIPTION	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES
Δ X					ANGLAR ±5°
Δ X					L ≤ 4 ±0.2
Δ X					4 < L ≤ 16 ±0.3
					16 < L ≤ 63 ±0.4
					L > 63 ±0.5

DSND	DATE	SCALE: N/A	MODEL TYPE:
DWN	DATE	VIEW:	SIM CARD CONN
CHKD	DATE	UNIT: mm	PART NO.:
APPD	DATE	SIZE: A4	DWG NO.: XKSIM-002-P7
KOSOD TECHNOLOGY CO., LTD			WEIGHT SHEET REVISION
			1.0g 1/1 A0